

# IS62WV1288ALL IS62WV1288BLL, IS65WV1288BLL



DECEMBER 2008

## 128K x 8 LOW VOLTAGE, ULTRA LOW POWER CMOS STATIC RAM

### FEATURES

- High-speed access time: 45ns, 55ns, 70ns
- CMOS low power operation:
  - 30 mW (typical) operating
  - 15  $\mu$ W (typical) CMOS standby
- TTL compatible interface levels
- Single power supply:
  - 1.65V--2.2V  $V_{DD}$  (62WV1288ALL)
  - 2.5V--3.6V  $V_{DD}$  (62WV1288BLL/ 65WV1288BLL)
- Fully static operation: no clock or refresh required
- Three state outputs
- Automotive and Industrial temperatures available
- Lead-free available

### DESCRIPTION

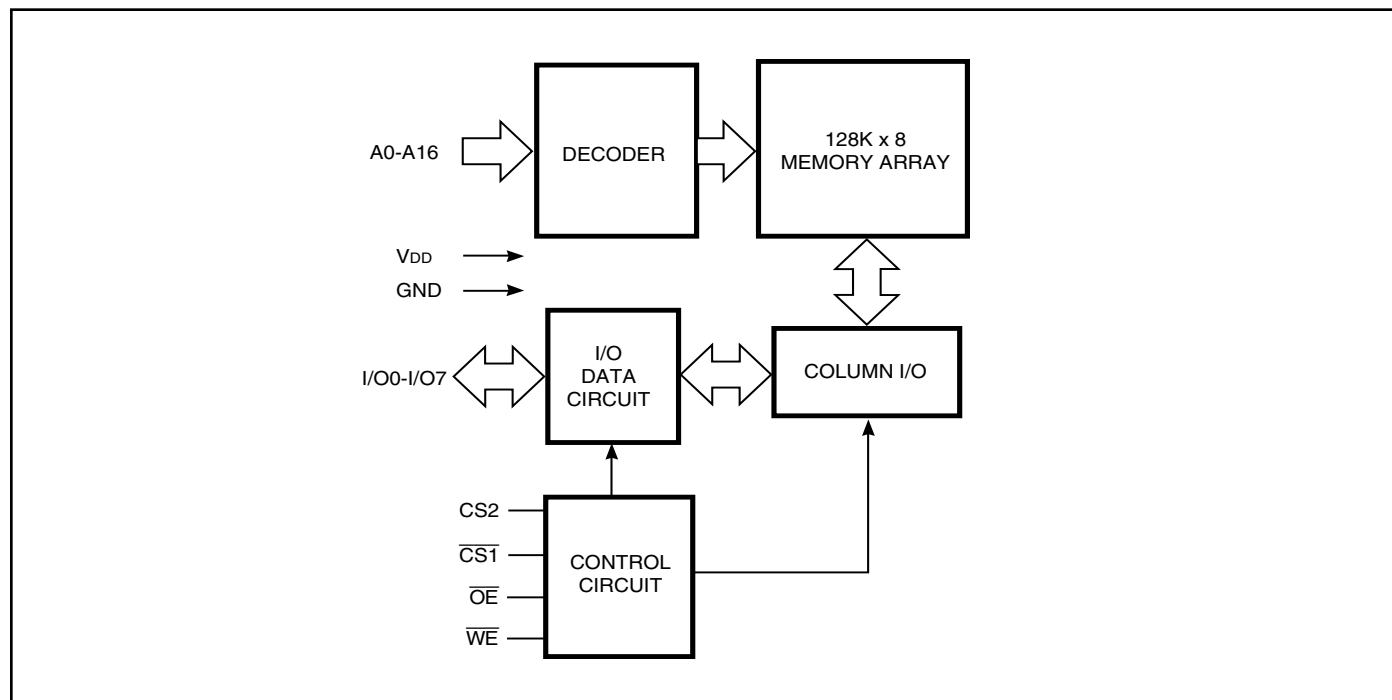
The *ISSI* IS62WV1288ALL / IS62/65WV1288BLL are high-speed, 1M bit static RAMs organized as 128K words by 8 bits. It is fabricated using *ISSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields high-performance and low power consumption devices.

When  $\overline{CS1}$  is HIGH (deselected) or when CS2 is LOW (deselected), the device assumes a standby mode at which the power dissipation can be reduced down with CMOS input levels.

Easy memory expansion is provided by using Chip Enable and Output Enable inputs. The active LOW Write Enable ( $\overline{WE}$ ) controls both writing and reading of the memory.

The IS62WV1288ALL and IS62/65WV1288BLL are packaged in the JEDEC standard 32-pin TSOP (TYPEI), sTSOP (TYPEI), SOP, and 36-pin mini BGA.

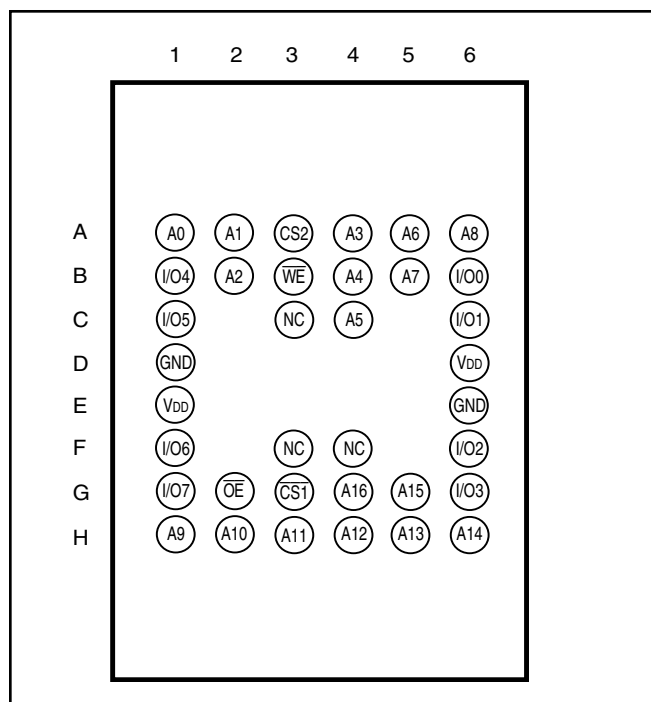
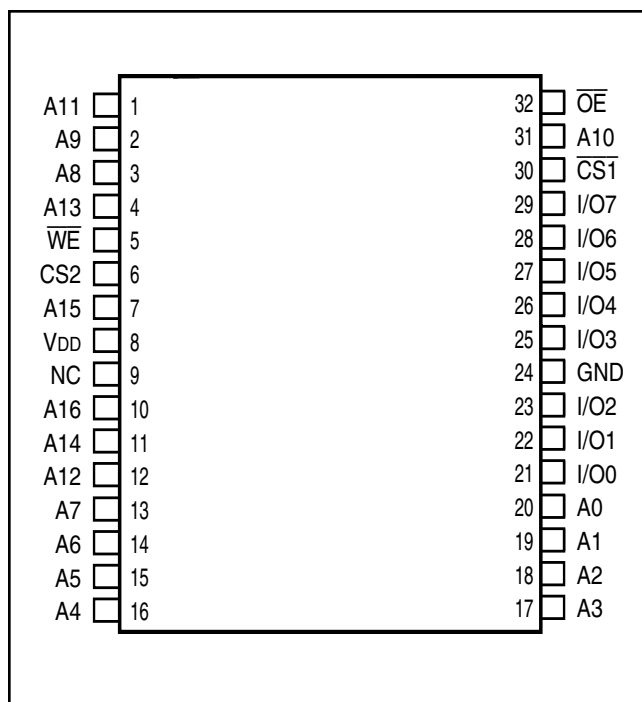
### FUNCTIONAL BLOCK DIAGRAM



Copyright © 2005 Integrated Silicon Solution, Inc. All rights reserved. ISSI reserves the right to make changes to this specification and its products at any time without notice. ISSI assumes no liability arising out of the application or use of any information, products or services described herein. Customers are advised to obtain the latest version of this device specification before relying on any published information and before placing orders for products.

## PIN CONFIGURATION

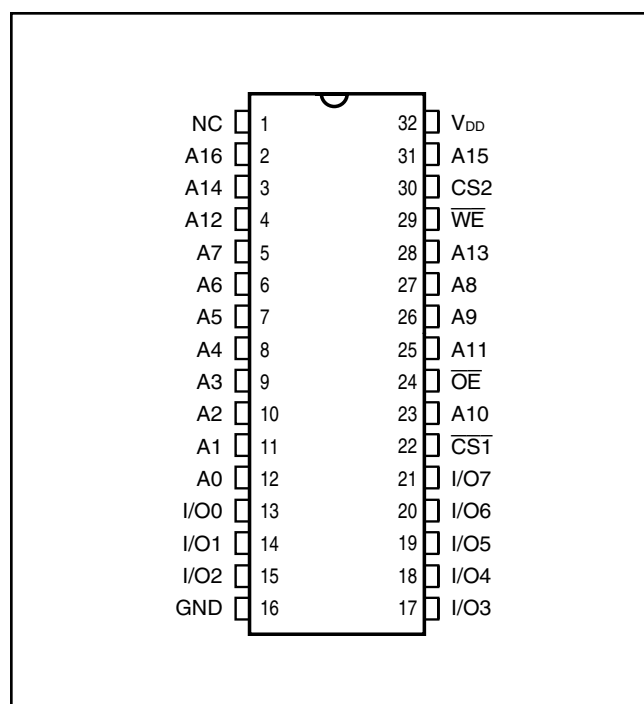
36-pin mini BGA (B) (6mm x 8mm)

32-pin TSOP (TYPE I) (T),  
32-pin sTSOP (TYPE I) (H)

## PIN DESCRIPTIONS

|           |                     |
|-----------|---------------------|
| A0-A16    | Address Inputs      |
| CS1       | Chip Enable 1 Input |
| CS2       | Chip Enable 2 Input |
| OE        | Output Enable Input |
| WE        | Write Enable Input  |
| I/O0-I/O7 | Input/Output        |
| NC        | No Connection       |
| VDD       | Power               |
| GND       | Ground              |

32-pin SOP (Q)



**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

| Symbol            | Parameter                            | Value                        | Unit |
|-------------------|--------------------------------------|------------------------------|------|
| V <sub>TERM</sub> | Terminal Voltage with Respect to GND | −0.2 to V <sub>DD</sub> +0.3 | V    |
| V <sub>DD</sub>   | V <sub>DD</sub> Related to GND       | −0.2 to +3.8                 | V    |
| T <sub>STG</sub>  | Storage Temperature                  | −65 to +150                  | °C   |
| P <sub>T</sub>    | Power Dissipation                    | 1.0                          | W    |

**Note:**

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**OPERATING RANGE (V<sub>DD</sub>)**

| Range         | Ambient Temperature | IS62WV1288ALL | IS62/65WV1288BLL |
|---------------|---------------------|---------------|------------------|
| Commercial    | 0°C to +70°C        | 1.65V - 2.2V  | 2.5V - 3.6V      |
| Industrial/A1 | −40°C to +85°C      | 1.65V - 2.2V  | 2.5V - 3.6V      |
| Automotive    | −40°C to +125°C     |               | 2.5V - 3.6V      |

**DC ELECTRICAL CHARACTERISTICS (Over Operating Range)**

| Symbol                         | Parameter           | Test Conditions                                             | V <sub>DD</sub> | Min. | Max.                  | Unit |
|--------------------------------|---------------------|-------------------------------------------------------------|-----------------|------|-----------------------|------|
| V <sub>OH</sub>                | Output HIGH Voltage | I <sub>OH</sub> = −0.1 mA                                   | 1.65-2.2V       | 1.4  | —                     | V    |
|                                |                     | I <sub>OH</sub> = −1 mA                                     | 2.5-3.6V        | 2.2  | —                     | V    |
| V <sub>OL</sub>                | Output LOW Voltage  | I <sub>OL</sub> = 0.1 mA                                    | 1.65-2.2V       | —    | 0.2                   | V    |
|                                |                     | I <sub>OL</sub> = 2.1 mA                                    | 2.5-3.6V        | —    | 0.4                   | V    |
| V <sub>IH</sub> <sup>(2)</sup> | Input HIGH Voltage  |                                                             | 1.65-2.2V       | 1.4  | V <sub>DD</sub> + 0.2 | V    |
|                                |                     |                                                             | 2.5-3.6V        | 2.2  | V <sub>DD</sub> + 0.3 | V    |
| V <sub>IL</sub> <sup>(1)</sup> | Input LOW Voltage   |                                                             | 1.65-2.2V       | −0.2 | 0.4                   | V    |
|                                |                     |                                                             | 2.5-3.6V        | −0.2 | 0.6                   | V    |
| I <sub>LI</sub>                | Input Leakage       | GND ≤ V <sub>IN</sub> ≤ V <sub>DD</sub>                     |                 | −1   | 1                     | μA   |
| I <sub>LO</sub>                | Output Leakage      | GND ≤ V <sub>OUT</sub> ≤ V <sub>DD</sub> , Outputs Disabled |                 | −1   | 1                     | μA   |

**Notes:**

1. Undershoot: −1.0V for pulse width less than 10 ns. Not 100% tested.
2. Overshoot: V<sub>DD</sub> + 1.0V for pulse width less than 10 ns. Not 100% tested.

**TRUTH TABLE**

| Mode                         | $\overline{WE}$ | $\overline{CS1}$ | CS2 | $\overline{OE}$ | I/O Operation    | V <sub>DD</sub> Current             |
|------------------------------|-----------------|------------------|-----|-----------------|------------------|-------------------------------------|
| Not Selected<br>(Power-down) | X               | H                | X   | X               | High-Z           | I <sub>SB1</sub> , I <sub>SB2</sub> |
|                              | X               | X                | L   | X               | High-Z           | I <sub>SB1</sub> , I <sub>SB2</sub> |
| Output Disabled              | H               | L                | H   | H               | High-Z           | I <sub>CC</sub>                     |
| Read                         | H               | L                | H   | L               | D <sub>OUT</sub> | I <sub>CC</sub>                     |
| Write                        | L               | L                | H   | X               | D <sub>IN</sub>  | I <sub>CC</sub>                     |



CAPACITANCE<sup>(1)</sup>

| Symbol           | Parameter                | Conditions            | Max. | Unit |
|------------------|--------------------------|-----------------------|------|------|
| C <sub>IN</sub>  | Input Capacitance        | V <sub>IN</sub> = 0V  | 8    | pF   |
| C <sub>OUT</sub> | Input/Output Capacitance | V <sub>OUT</sub> = 0V | 10   | pF   |

Note:

1. Tested initially and after any design or process changes that may affect these parameters.

AC TEST CONDITIONS

| Parameter                                   | 62WV1288ALL                   | 62/65WV1288BLL                |
|---------------------------------------------|-------------------------------|-------------------------------|
|                                             | (Unit)                        | (Unit)                        |
| Input Pulse Level                           | 0.4V to V <sub>DD</sub> -0.2V | 0.4V to V <sub>DD</sub> -0.3V |
| Input Rise and Fall Times                   | 5 ns                          | 5ns                           |
| Input and Output Timing and Reference Level | V <sub>REF</sub>              | V <sub>REF</sub>              |
| Output Load                                 | See Figures 1 and 2           | See Figures 1 and 2           |

|                  | 1.65V - 2.2V | 2.5V - 3.6V |
|------------------|--------------|-------------|
| R1(Ω)            | 3070         | 3070        |
| R2(Ω)            | 3150         | 3150        |
| V <sub>REF</sub> | 0.9V         | 1.5V        |
| V <sub>TM</sub>  | 1.8V         | 2.8V        |

AC TEST LOADS

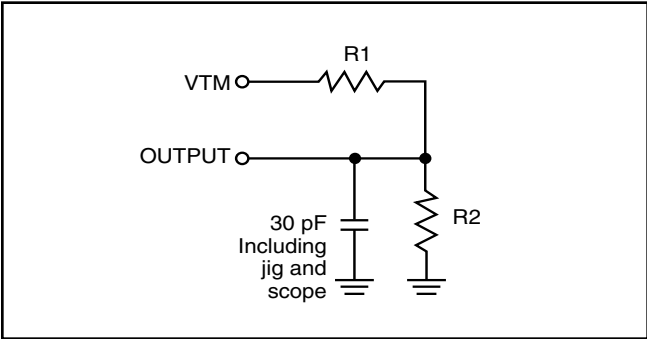


Figure 1

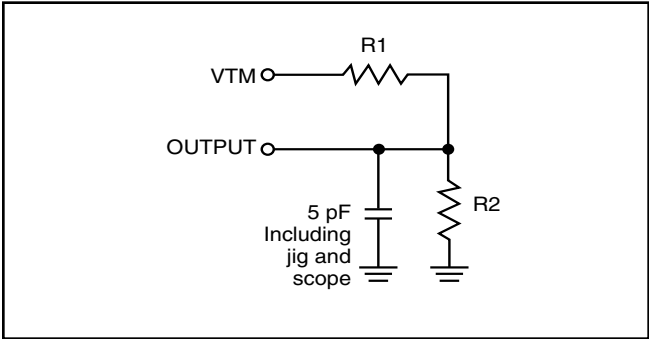


Figure 2

# IS62WV1288ALL, IS62WV1288BLL, IS65WV1288BLL

## POWER SUPPLY CHARACTERISTICS<sup>(1)</sup> (Over Operating Range)

### 1.65V - 2.2V

| Symbol           | Parameter                                        | Test Conditions                                                                                                                                          |                                     | Max.<br>70 ns | Unit |
|------------------|--------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------|---------------|------|
| I <sub>CC</sub>  | V <sub>DD</sub> Dynamic Operating Supply Current | V <sub>DD</sub> = Max.,<br>I <sub>OUT</sub> = 0 mA, f = f <sub>MAX</sub>                                                                                 | Com.<br>Ind.<br>typ. <sup>(2)</sup> | 8<br>8<br>5   | mA   |
| I <sub>CC1</sub> | Operating Supply Current                         | V <sub>DD</sub> = Max.,<br>I <sub>OUT</sub> = 0 mA, f = 0                                                                                                | Com.<br>Ind.                        | 5<br>5        | mA   |
| I <sub>SB1</sub> | TTL Standby Current (TTL Inputs)                 | V <sub>DD</sub> = Max.,<br>V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub><br>CS1 = V <sub>IH</sub> , CS2 = V <sub>IL</sub> ,<br>f = 1 MHz          | Com.<br>Ind.                        | 0.8<br>0.8    | mA   |
| I <sub>SB2</sub> | CMOS Standby Current (CMOS Inputs)               | V <sub>DD</sub> = Max.,<br>CS1 ≥ V <sub>DD</sub> - 0.2V,<br>CS2 ≤ 0.2V,<br>V <sub>IN</sub> ≥ V <sub>DD</sub> - 0.2V, or<br>V <sub>IN</sub> ≤ 0.2V, f = 0 | Com.<br>Ind.<br>typ. <sup>(2)</sup> | 10<br>10<br>5 | μA   |

#### Note:

- At f = f<sub>MAX</sub>, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.
- Typical values are measured at V<sub>DD</sub>=1.8V, T<sub>A</sub>=25°C. Not 100% tested.

## POWER SUPPLY CHARACTERISTICS<sup>(1)</sup> (Over Operating Range)

### 2.5V - 3.6V

| Symbol           | Parameter                                        | Test Conditions                                                                                                                                          |                                              | Max.<br>45ns   | Max.<br>55 ns        | Unit |
|------------------|--------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------|----------------|----------------------|------|
| I <sub>CC</sub>  | V <sub>DD</sub> Dynamic Operating Supply Current | V <sub>DD</sub> = Max.,<br>I <sub>OUT</sub> = 0 mA, f = f <sub>MAX</sub>                                                                                 | Com.<br>Ind./A1<br>A3<br>typ. <sup>(2)</sup> | 17<br>17<br>12 | 15<br>15<br>35<br>10 | mA   |
| I <sub>CC1</sub> | Operating Supply Current                         | V <sub>DD</sub> = Max.,<br>I <sub>OUT</sub> = 0 mA, f = 0                                                                                                | Com.<br>Ind./A1<br>A3                        | 5<br>5         | 5<br>5<br>7          | mA   |
| I <sub>SB1</sub> | TTL Standby Current (TTL Inputs)                 | V <sub>DD</sub> = Max.,<br>V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub><br>CS1 = V <sub>IH</sub> , CS2 = V <sub>IL</sub> ,<br>f = 1 MHz          | Com.<br>Ind./A1<br>A3                        | 0.8<br>0.8     | 0.8<br>0.8<br>3      | mA   |
| I <sub>SB2</sub> | CMOS Standby Current (CMOS Inputs)               | V <sub>DD</sub> = Max.,<br>CS1 ≥ V <sub>DD</sub> - 0.2V,<br>CS2 ≤ 0.2V,<br>V <sub>IN</sub> ≥ V <sub>DD</sub> - 0.2V, or<br>V <sub>IN</sub> ≤ 0.2V, f = 0 | Com.<br>Ind./A1<br>A3<br>typ. <sup>(2)</sup> | 10<br>10<br>5  | 10<br>10<br>75<br>5  | μA   |

#### Note:

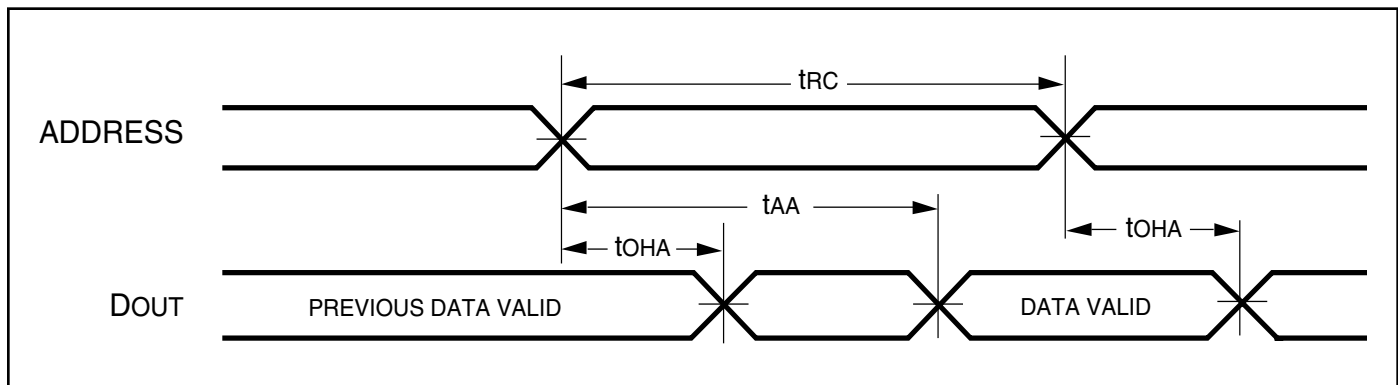
- At f = f<sub>MAX</sub>, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.
- Typical values are measured at V<sub>DD</sub>=3.0V, T<sub>A</sub>=25°C. Not 100% tested.

**READ CYCLE SWITCHING CHARACTERISTICS<sup>(1)</sup>** (Over Operating Range)

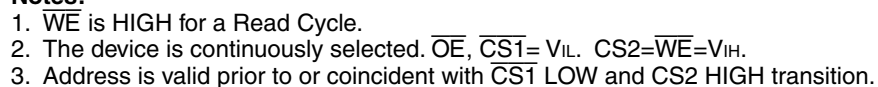
| Symbol                      | Parameter                        | 45 ns |      | 55 ns |      | 70 ns |      | Unit |
|-----------------------------|----------------------------------|-------|------|-------|------|-------|------|------|
|                             |                                  | Min.  | Max. | Min.  | Max. | Min.  | Max. |      |
| $t_{RC}$                    | Read Cycle Time                  | 45    | —    | 55    | —    | 70    | —    | ns   |
| $t_{AA}$                    | Address Access Time              | —     | 45   | —     | 55   | —     | 70   | ns   |
| $t_{OHA}$                   | Output Hold Time                 | 10    | —    | 10    | —    | 10    | —    | ns   |
| $t_{ACS1}/t_{ACS2}$         | CS1/CS2 Access Time              | —     | 45   | —     | 55   | —     | 70   | ns   |
| $t_{DOE}$                   | $\overline{OE}$ Access Time      | —     | 20   | —     | 25   | —     | 35   | ns   |
| $t_{HZOE}^{(2)}$            | $\overline{OE}$ to High-Z Output | 0     | 15   | 0     | 20   | 0     | 25   | ns   |
| $t_{LZOE}^{(2)}$            | $\overline{OE}$ to Low-Z Output  | 5     | —    | 5     | —    | 5     | —    | ns   |
| $t_{HZCS1}/t_{HZCS2}^{(2)}$ | CS1/CS2 to High-Z Output         | 0     | 15   | 0     | 20   | 0     | 25   | ns   |
| $t_{LZCS1}/t_{LZCS2}^{(2)}$ | CS1/CS2 to Low-Z Output          | 5     | —    | 10    | —    | 10    | —    | ns   |

**Notes:**

1. Test conditions assume signal transition times of 5 ns or less, timing reference levels of 0.9V/1.5V, input pulse levels of 0.4 to  $V_{DD}-0.2V/V_{DD}-0.3V$  and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured  $\pm 500$  mV from steady-state voltage. Not 100% tested.

**AC WAVEFORMS****READ CYCLE NO. 1<sup>(1,2)</sup>** (Address Controlled) ( $\overline{CS1} = \overline{OE} = V_{IL}$ ,  $CS2 = \overline{WE} = V_{IH}$ )

**READ CYCLE NO. 2<sup>(1,3)</sup>** ( $\overline{\text{CS1}}$ , CS2,  $\overline{\text{OE}}$  Controlled)

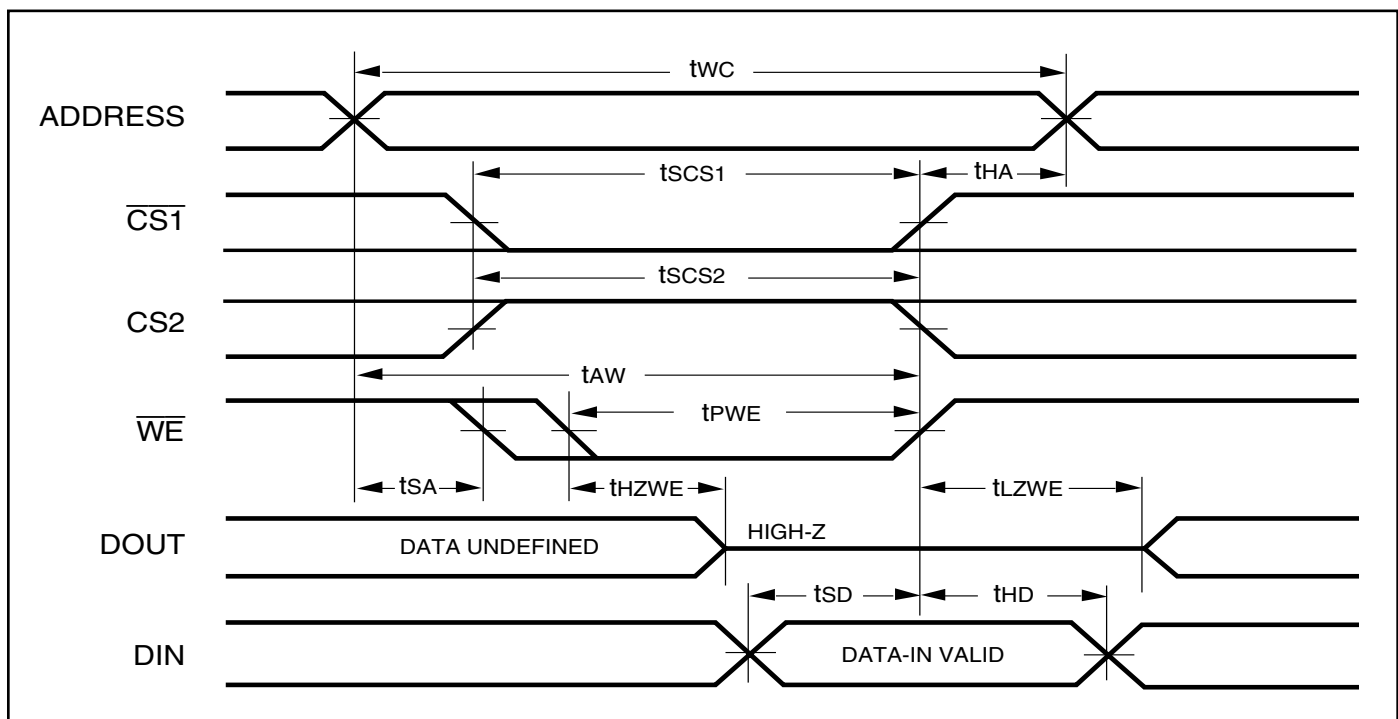


**WRITE CYCLE SWITCHING CHARACTERISTICS<sup>(1,2)</sup>** (Over Operating Range)

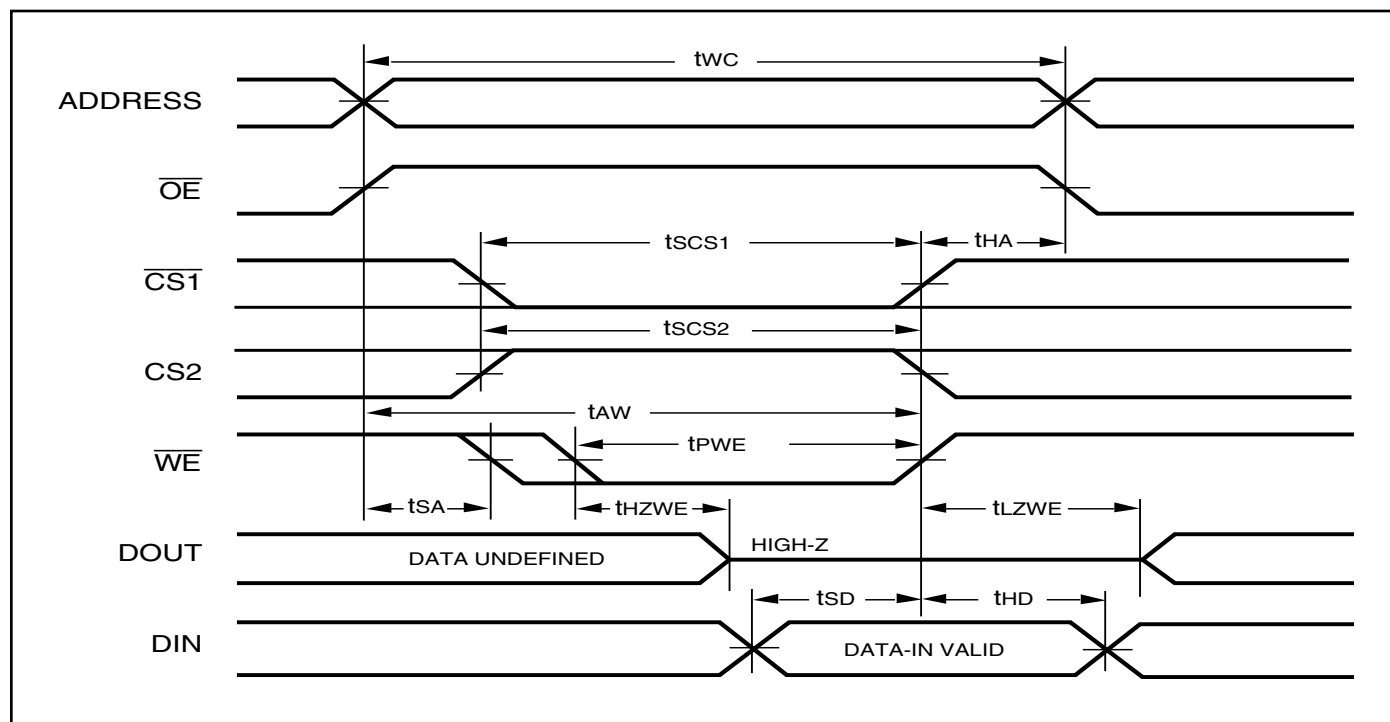
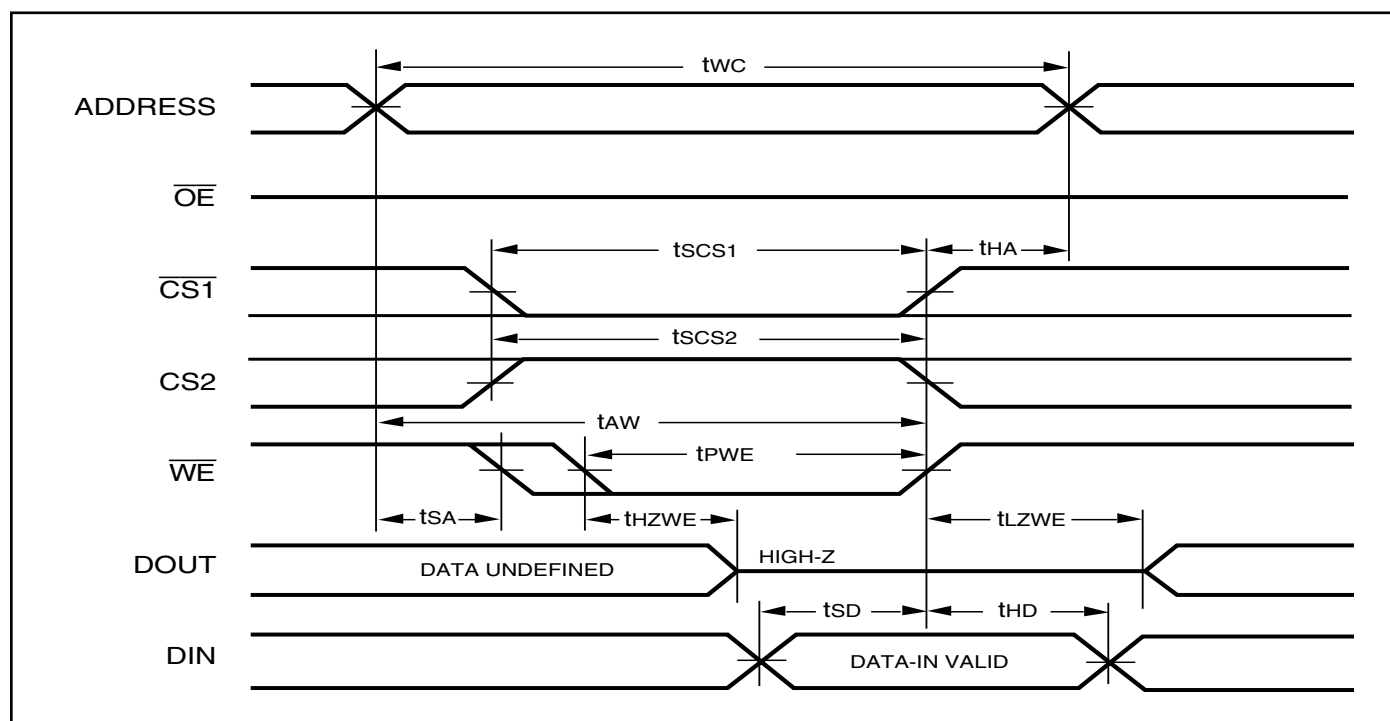
| Symbol                           | Parameter                       | 45 ns |      | 55 ns |      | 70 ns |      | Unit |
|----------------------------------|---------------------------------|-------|------|-------|------|-------|------|------|
|                                  |                                 | Min.  | Max. | Min.  | Max. | Min.  | Max. |      |
| t <sub>WC</sub>                  | Write Cycle Time                | 45    | —    | 55    | —    | 70    | —    | ns   |
| t <sub>SCS1/tSCS2</sub>          | CS1/CS2 to Write End            | 35    | —    | 45    | —    | 60    | —    | ns   |
| t <sub>AW</sub>                  | Address Setup Time to Write End | 35    | —    | 45    | —    | 60    | —    | ns   |
| t <sub>HA</sub>                  | Address Hold from Write End     | 0     | —    | 0     | —    | 0     | —    | ns   |
| t <sub>SA</sub>                  | Address Setup Time              | 0     | —    | 0     | —    | 0     | —    | ns   |
| t <sub>PWE</sub>                 | WE Pulse Width                  | 35    | —    | 40    | —    | 50    | —    | ns   |
| t <sub>SD</sub>                  | Data Setup to Write End         | 20    | —    | 25    | —    | 30    | —    | ns   |
| t <sub>HD</sub>                  | Data Hold from Write End        | 0     | —    | 0     | —    | 0     | —    | ns   |
| t <sub>HZWE</sub> <sup>(3)</sup> | WE LOW to High-Z Output         | —     | 20   | —     | 20   | —     | 20   | ns   |
| t <sub>LZWE</sub> <sup>(3)</sup> | WE HIGH to Low-Z Output         | 5     | —    | 5     | —    | 5     | —    | ns   |

**Notes:**

1. Test conditions assume signal transition times of 5 ns or less, timing reference levels of 0.9V/1.5V, input pulse levels of 0.4V to V<sub>DD</sub>-0.2V/V<sub>DD</sub>-0.3V and output loading specified in Figure 1.
2. The internal write time is defined by the overlap of CS1 LOW, CS2 HIGH, and WE LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.
3. Tested with the load in Figure 2. Transition is measured  $\pm 500$  mV from steady-state voltage. Not 100% tested.

**AC WAVEFORMS**
**WRITE CYCLE NO. 1** ( $\overline{\text{CS1}}$ /CS2 Controlled,  $\overline{\text{OE}}$  = HIGH or LOW)


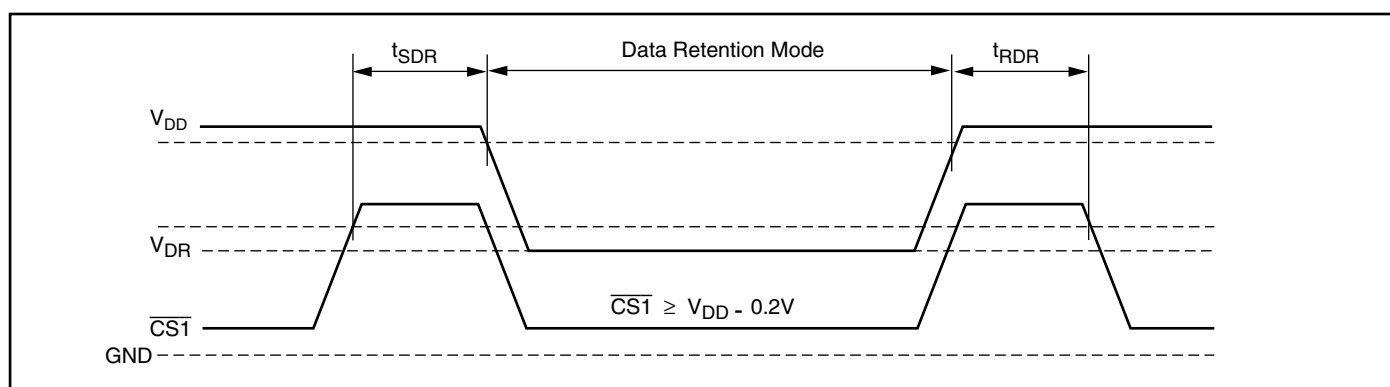
## AC WAVEFORMS

WRITE CYCLE NO. 2 ( $\overline{WE}$  Controlled:  $\overline{OE}$  is HIGH During Write Cycle)WRITE CYCLE NO. 3 ( $\overline{WE}$  Controlled:  $\overline{OE}$  is LOW During Write Cycle)

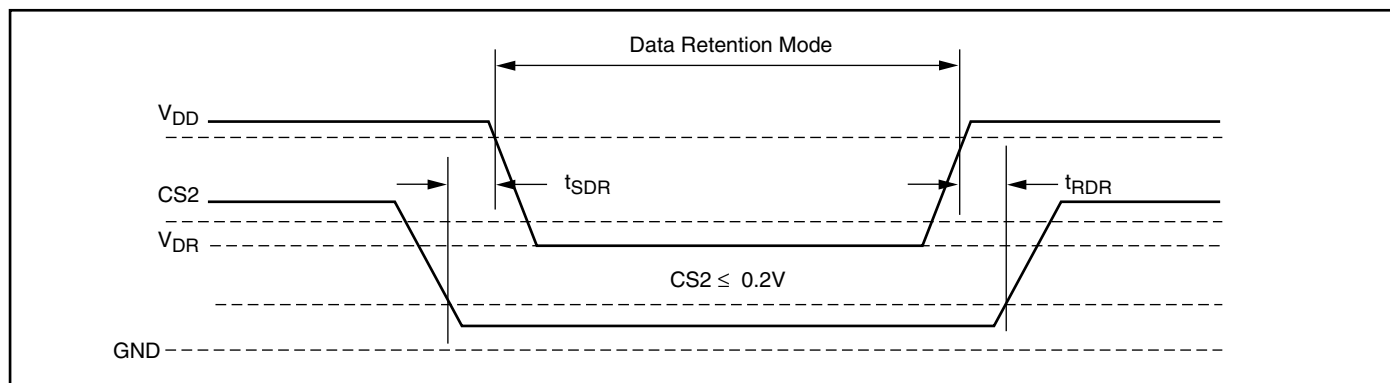
## DATA RETENTION SWITCHING CHARACTERISTICS

| Symbol    | Parameter                   | Test Condition                                        | Min.                  | Max.          | Unit    |
|-----------|-----------------------------|-------------------------------------------------------|-----------------------|---------------|---------|
| $V_{DR}$  | $V_{DD}$ for Data Retention | See Data Retention Waveform                           | 1.2                   | 3.6           | V       |
| $I_{DR}$  | Data Retention Current      | $V_{DD} = 1.2V$ , $\overline{CS1} \geq V_{DD} - 0.2V$ | Com.<br>Ind./A1<br>A3 | 5<br>10<br>75 | $\mu A$ |
| $t_{SDR}$ | Data Retention Setup Time   | See Data Retention Waveform                           | 0                     | —             | ns      |
| $t_{RDR}$ | Recovery Time               | See Data Retention Waveform                           | $t_{RC}$              | —             | ns      |

### DATA RETENTION WAVEFORM ( $\overline{CS1}$ Controlled)



### DATA RETENTION WAVEFORM (CS2 Controlled)



# IS62WV1288ALL, IS62WV1288BLL, IS65WV1288BLL

## ORDERING INFORMATION

### IS62WV1288ALL (1.65V - 2.2V)

**Industrial Range: -40°C to +85°C**

| Speed (ns) | Order Part No.     | Package              |
|------------|--------------------|----------------------|
| 70         | IS62WV1288ALL-70BI | mini BGA (6mm x 8mm) |
|            | IS62WV1288ALL-70HI | sTSOP, TYPE I        |

### IS62WV1288BLL (2.5V-3.6V)

**Industrial Range: -40°C to +85°C**

| Speed (ns) | Order Part No.      | Package                  |
|------------|---------------------|--------------------------|
| 45         | IS62WV1288BLL-45TI  | TSOP, TYPE I             |
|            | IS62WV1288BLL-45BI  | mini BGA (6mm x 8mm)     |
|            | IS62WV1288BLL-45HI  | sTSOP, TYPE I            |
|            | IS62WV1288BLL-45HLI | sTSOP, TYPE I, Lead-free |
|            | IS62WV1288BLL-45QI  | SOP                      |
| 55         | IS62WV1288BLL-55TI  | TSOP, TYPE I             |
|            | IS62WV1288BLL-55TLI | TSOP, TYPE I, Lead-free  |
|            | IS62WV1288BLL-55BI  | mini BGA (6mm x 8mm)     |
|            | IS62WV1288BLL-55HI  | sTSOP, TYPE I            |
|            | IS62WV1288BLL-55HLI | sTSOP, TYPE I, Lead-free |
|            | IS62WV1288BLL-55QI  | SOP                      |
|            | IS62WV1288BLL-55QLI | SOP, Lead-free           |

### IS65WV1288BLL (2.5V-3.6V)

**A1 Range: -40°C to +85°C**

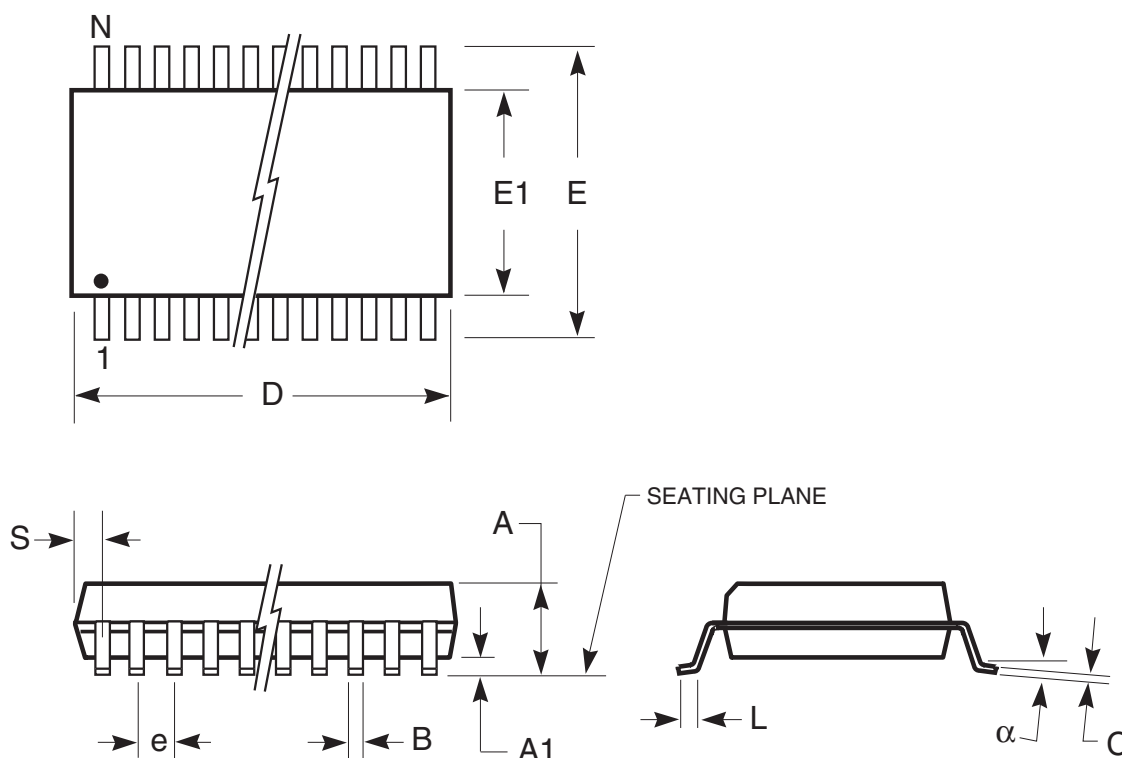
| Speed (ns) | Order Part No.       | Package                  |
|------------|----------------------|--------------------------|
| 55         | IS65WV1288BLL-55HLA1 | sTSOP, TYPE I, Lead-free |
|            | IS65WV1288BLL-55TLA1 | TSOP, TYPE I, Lead-free  |

**A3 Range: -40°C to +125°C**

| Speed (ns) | Order Part No.       | Package                  |
|------------|----------------------|--------------------------|
| 55         | IS65WV1288BLL-55HLA3 | sTSOP, TYPE I, Lead-free |

# PACKAGING INFORMATION

450-mil Plastic SOP  
Package Code: Q (32-pin)



|           | MILLIMETERS |       | INCHES    |       |
|-----------|-------------|-------|-----------|-------|
| Symbol    | Min.        | Max.  | Min.      | Max.  |
| No. Leads | 32          |       |           |       |
| A         | —           | 3.00  | —         | 0.118 |
| A1        | 0.10        | —     | 0.004     | —     |
| B         | 0.36        | 0.51  | 0.014     | 0.020 |
| C         | 0.15        | 0.30  | 0.006     | 0.012 |
| D         | 20.14       | 20.75 | 0.793     | 0.817 |
| E         | 13.87       | 14.38 | 0.546     | 0.566 |
| E1        | 11.18       | 11.43 | 0.440     | 0.450 |
| e         | 1.27 BSC    |       | 0.050 BSC |       |
| L         | 0.58        | 0.99  | 0.023     | 0.039 |
| $\alpha$  | 0°          | 10°   | 0°        | 10°   |
| S         | —           | 0.86  | —         | 0.034 |

## Notes:

1. Controlling dimension: inches, unless otherwise specified.
2. BSC = Basic lead spacing between centers.
3. Dimensions D and E1 do not include mold flash protrusions and should be measured from the bottom of the package.
4. Formed leads shall be planar with respect to one another within 0.004 inches at the seating plane.

Copyright © 2003 Integrated Silicon Solution, Inc. All rights reserved. ISSI reserves the right to make changes to this specification and its products at any time without notice. ISSI assumes no liability arising out of the application or use of any information, products or services described herein. Customers are advised to obtain the latest version of this device specification before relying on any published information and before placing orders for products.

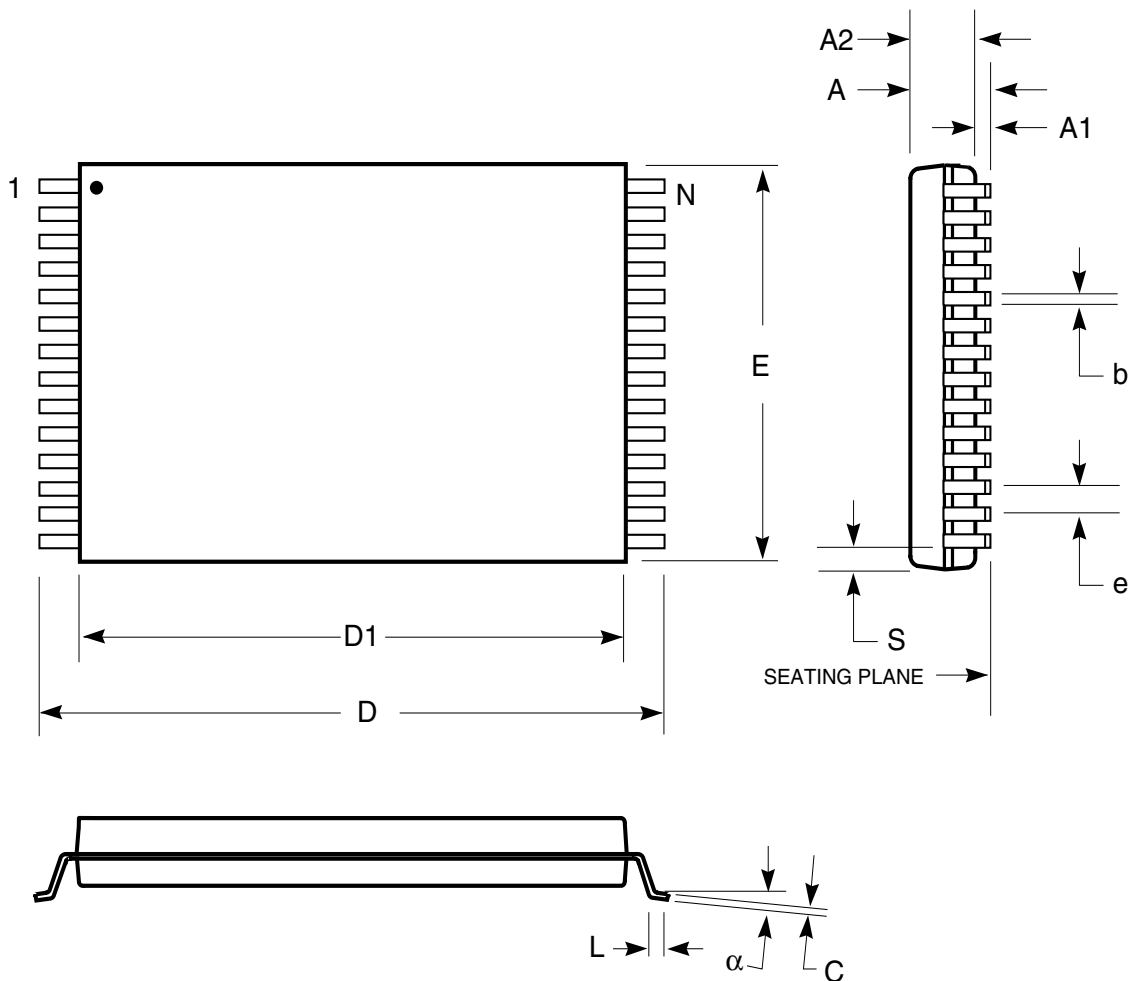
Integrated Silicon Solution, Inc. — [www.issi.com](http://www.issi.com) — 1-800-379-4774

Rev. C  
06/13/03

# PACKAGING INFORMATION

Plastic STSOP - 32 pins

Package Code: H (Type I)



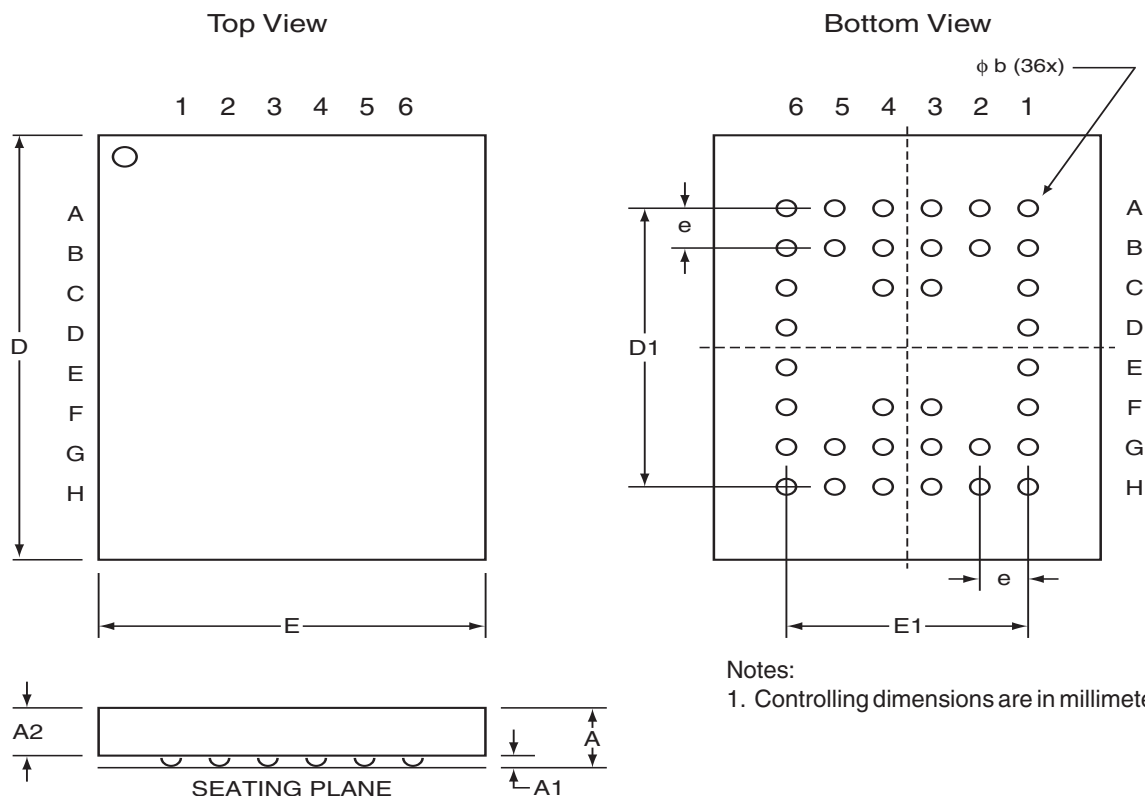
| Plastic STSOP (H - Type I) |             |       |            |        |
|----------------------------|-------------|-------|------------|--------|
|                            | Millimeters |       | Inches     |        |
| Symbol                     | Min         | Max   | Min        | Max    |
| Ref. Std.                  |             |       |            |        |
| N                          | 32          |       |            |        |
| A                          | —           | 1.25  | —          | 0.049  |
| A1                         | 0.05        | —     | 0.002      | —      |
| A2                         | 0.95        | 1.05  | 0.037      | 0.041  |
| b                          | 0.17        | 0.23  | 0.007      | 0.009  |
| C                          | 0.14        | 0.16  | 0.0055     | 0.0063 |
| D                          | 13.20       | 13.60 | 0.520      | 0.535  |
| D1                         | 11.70       | 11.90 | 0.461      | 0.469  |
| E                          | 7.90        | 8.10  | 0.311      | 0.319  |
| e                          | 0.50 BSC    |       | 0.020 BSC  |        |
| L                          | 0.30        | 0.70  | 0.012      | 0.028  |
| S                          | 0.28 Typ.   |       | 0.011 Typ. |        |
| α                          | 0°          | 5°    | 0°         | 5°     |

## Notes:

1. Controlling dimension: millimeters, unless otherwise specified.
2. BSC = Basic lead spacing between centers.
3. Dimensions D1 and E do not include mold flash protrusions and should be measured from the bottom of the package.
4. Formed leads shall be planar with respect to one another within 0.004 inches at the seating plane.

## PACKAGING INFORMATION

## Mini Ball Grid Array

**Package Code: B (36-pin)**

Notes:  
1. Controlling dimensions are in millimeters.

## mBGA - 6mm x 8mm

| MILLIMETERS |         |      |      | INCHES   |       |       |
|-------------|---------|------|------|----------|-------|-------|
| Sym.        | Min.    | Typ. | Max. | Min.     | Typ.  | Max.  |
| N0.         |         |      |      |          |       |       |
| Leads       | 36      |      |      | 36       |       |       |
| A           | —       | —    | 1.20 | —        | —     | 0.047 |
| A1          | 0.24    | —    | 0.30 | 0.009    | —     | 0.012 |
| A2          | 0.60    | —    | —    | 0.024    | —     | —     |
| D           | 7.90    | 8.00 | 8.10 | 0.311    | 0.315 | 0.319 |
| D1          | 5.25BSC |      |      | 0.207BSC |       |       |
| E           | 5.90    | 6.00 | 6.10 | 0.232    | 0.236 | 0.240 |
| E1          | 3.75BSC |      |      | 0.148BSC |       |       |
| e           | 0.75BSC |      |      | 0.030BSC |       |       |
| b           | 0.30    | 0.35 | 0.40 | 0.012    | 0.014 | 0.016 |

**mBGA - 8mm x 10mm**

|              | MILLIMETER |       |       | INCHES   |       |       |
|--------------|------------|-------|-------|----------|-------|-------|
| Sym.         | Min.       | Typ.  | Max.  | Min.     | Typ.  | Max.  |
| N0.<br>Leads |            | 36    |       |          | 36    |       |
| A            | —          | —     | 1.20  | —        | —     | 0.047 |
| A1           | 0.24       | —     | 0.30  | 0.009    | —     | 0.012 |
| A2           | 0.60       | —     | —     | 0.024    | —     | —     |
| D            | 9.90       | 10.00 | 10.10 | 0.390    | 0.394 | 0.398 |
| D1           | 5.25BSC    |       |       | .207BSC  |       |       |
| E            | 7.90       | 8.00  | 8.10  | 0.311    | 0.315 | 0.319 |
| E1           | 3.75BSC    |       |       | 0.148BSC |       |       |
| e            | 0.75BSC    |       |       | 0.030BSC |       |       |
| b            | 0.30       | 0.35  | 0.40  | 0.012    | 0.014 | 0.016 |

Copyright © 2003 Integrated Silicon Solution, Inc. All rights reserved. ISSI reserves the right to make changes to this specification and its products at any time without notice. ISSI assumes no liability arising out of the application or use of any information, products or services described herein. Customers are advised to obtain the latest version of this device specification before relying on any published information and before placing orders for products.

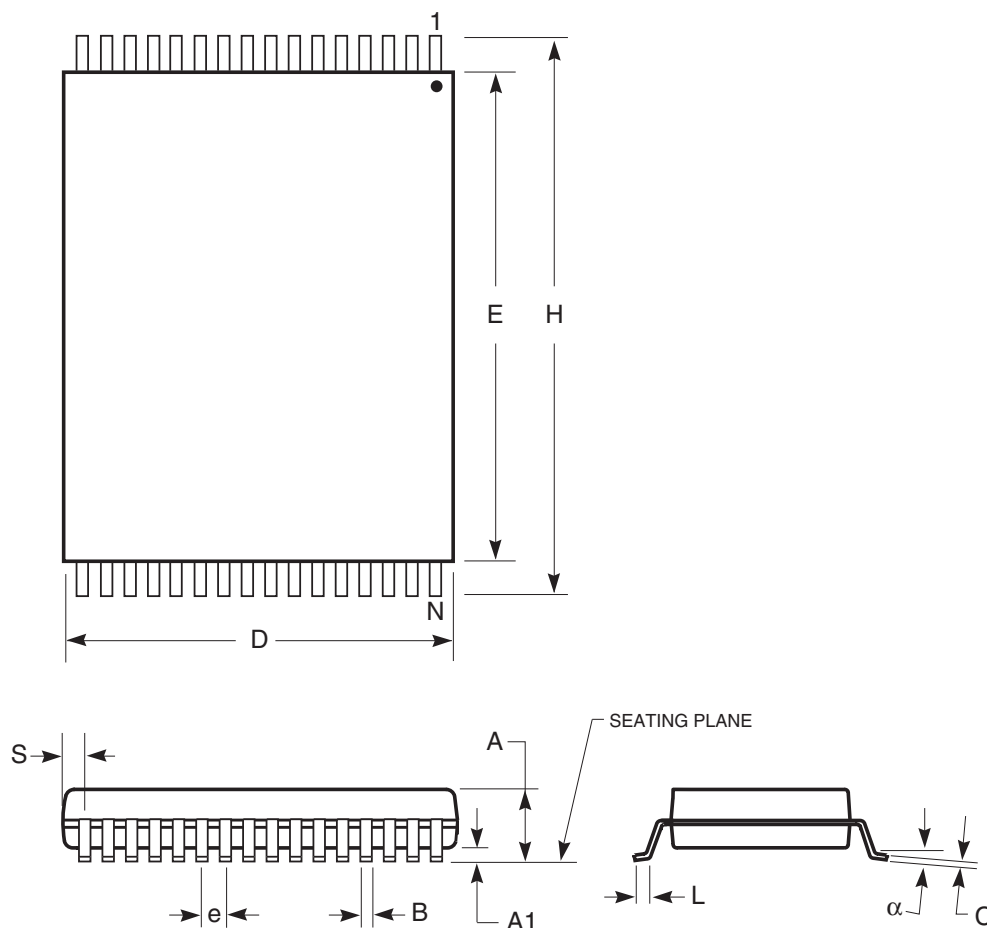
**Integrated Silicon Solution, Inc. — [www.issi.com](http://www.issi.com) — 1-800-379-4774**

Rev. E  
01/15/03

# PACKAGING INFORMATION

Plastic TSOP-Type I

Package Code: T (32-pin)



|           | MILLIMETERS |       | INCHES    |       |
|-----------|-------------|-------|-----------|-------|
| Symbol    | Min.        | Max.  | Min.      | Max.  |
| No. Leads | 32          |       |           |       |
| A         | —           | 1.20  | —         | 0.047 |
| A1        | 0.05        | 0.25  | 0.002     | 0.010 |
| B         | 0.17        | 0.23  | 0.007     | 0.009 |
| C         | 0.12        | 0.17  | 0.005     | 0.007 |
| D         | 7.90        | 8.10  | 0.311     | 0.319 |
| E         | 18.30       | 18.50 | 0.720     | 0.728 |
| H         | 19.80       | 20.20 | 0.780     | 0.795 |
| e         | 0.50 BSC    |       | 0.020 BSC |       |
| L         | 0.40        | 0.60  | 0.016     | 0.024 |
| α         | 0°          | 8°    | 0°        | 8°    |
| S         | 0.25 REF    |       | 0.010 REF |       |

## Notes:

1. Controlling dimension: millimeters, unless otherwise specified.
2. BSC = Basic lead spacing between centers.
3. Dimensions D and E do not include mold flash protrusions and should be measured from the bottom of the package.
4. Formed leads shall be planar with respect to one another within 0.004 inches at the seating plane.

Copyright © 2003 Integrated Silicon Solution, Inc. All rights reserved. ISSI reserves the right to make changes to this specification and its products at any time without notice. ISSI assumes no liability arising out of the application or use of any information, products or services described herein. Customers are advised to obtain the latest version of this device specification before relying on any published information and before placing orders for products.